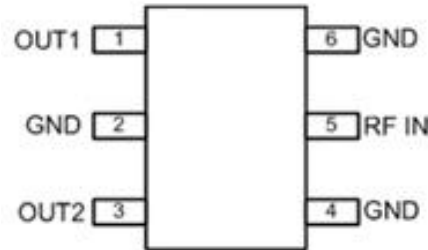


## GaAs MMIC monolithic integrated 0 degree power divider , 2400-2900M Hz

### Performance characteristics

- Frequency range: 2400-2900MHz
- Insertion loss : 0.5 dB
- Isolation: 30dB
- Phase imbalance:0.2°
- Amplitude imbalance: 0.1 dB
- 50Ohm input / output
- Chip size: SOT23

### Functional Block Diagram



### Product Introduction

GPD-024029A-ST23 monolithic integrated 0 degree power divider has low insertion loss, good isolation, and low phase and amplitude imbalance in the frequency range of 2400 ~ 2900MHz , which is very suitable for microwave hybrid integrated circuits and multi-chip modules. This chip adopts SOT23 plastic surface mount package, and the surface of the pin pad is tinned, which is suitable for reflow soldering installation process.

### Electrical performance parameters ( TA = +25°C)

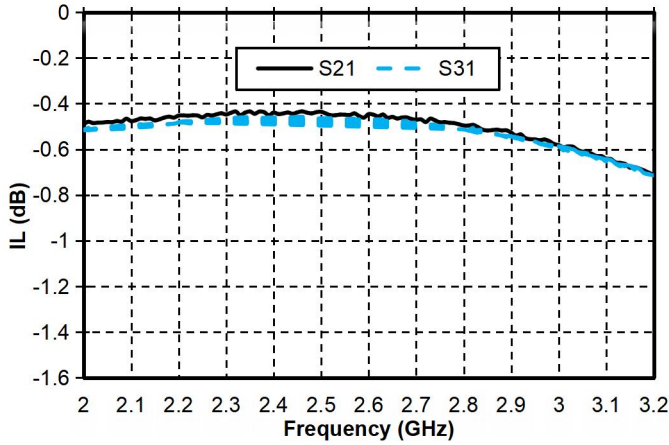
Index	Minimum	Typical Value	Maximum	Test frequency	Unit
Insertion loss/isolation	-	0.4 / 24	-	2400 MHz	dB
	-	0.4 / 30	-	2500 MHz	dB
	-	0.5 / 36	-	2650 MHz	dB
	-	0.5 / 24	-	2800 MHz	dB
	-	0.5 / 20	-	2900 MHz	dB
Phase imbalance/amplitude imbalance	-	0.2 / 0.1	-	2400 MHz	Deg .dB
	-	0.2 / 0.1	-	2500 MHz	Deg .dB
	-	0.2 / 0.1	-	2650 MHz	Deg .dB
	-	0.2 / 0.1	-	2800 MHz	Deg .dB
	-	0.2 / 0.1	-	2900 MHz	Deg .dB
Input return loss / output return loss	-	20 / 36	-	2400 MHz	dB
	-	21 / 31	-	2500 MHz	dB
	-	20 / 25	-	2650 MHz	dB
	-	18 / 22	-	2800 MHz	dB
	-	17 / 20	-	2900 MHz	dB

\* The inherent loss of the power divider has been deducted .

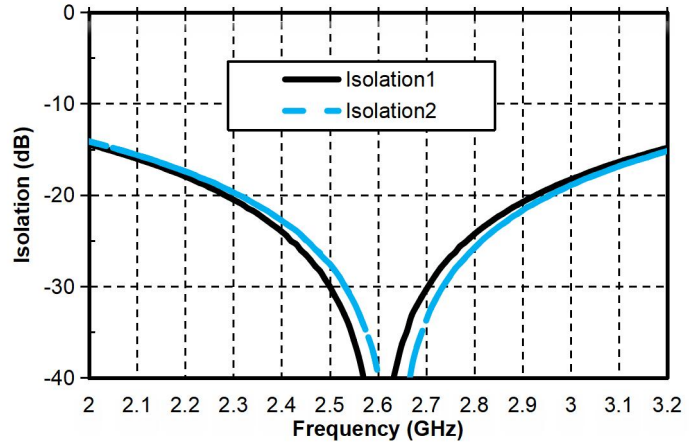
## GaAs MMIC monolithic integrated 0 degree power divider , 2400-2900M Hz

To test the curve

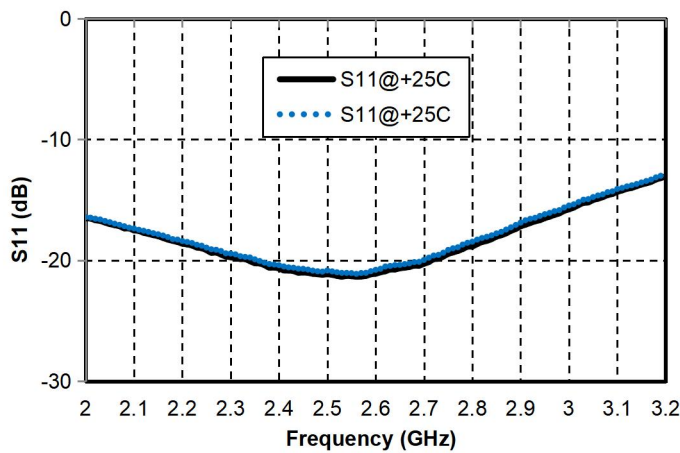
Insertion Loss vs. Operating Frequency



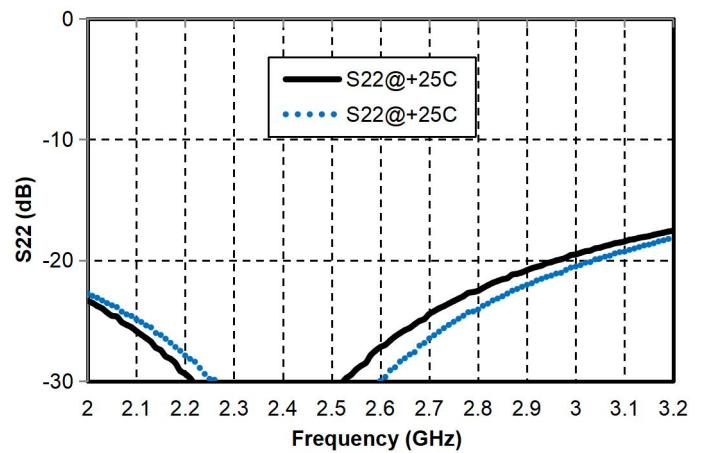
Isolation vs. Operating Frequency



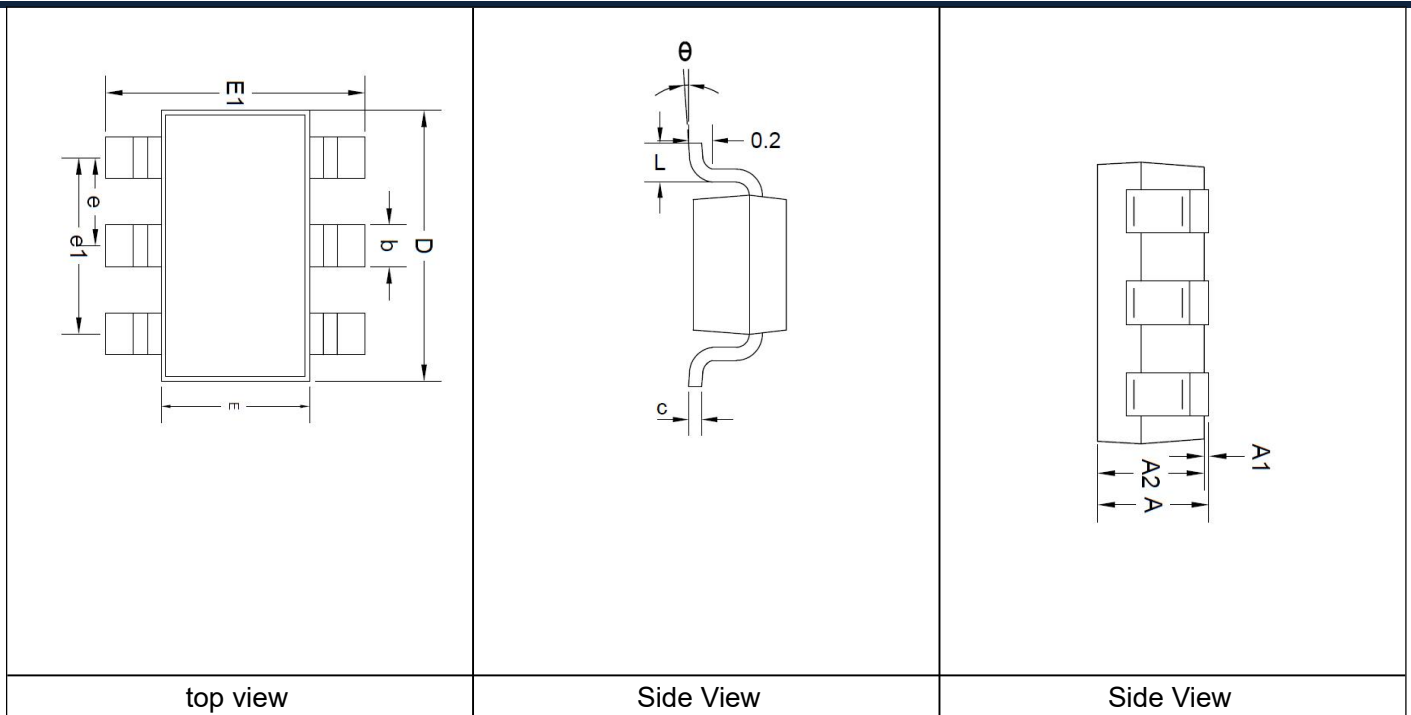
Input Return Loss vs. Operating Frequency



Output Return Loss vs. Operating Frequency



Dimensions



## GaAs MMIC monolithic integrated 0 degree power divider , 2400-2900M Hz

### Structure size

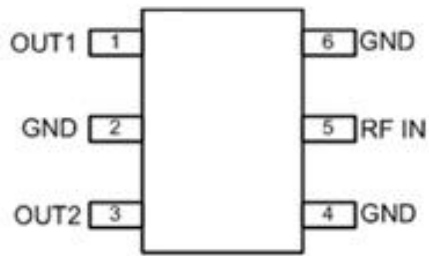
Annotation	Minimum	Standard	Saximum	Annotation	Minimum	Standard	Maximum
A	1.050	1.150	1.250	E	1.500	1.600	1.700
A1	0.00	0.05	0.100	E1	2.650	2.800	2.950
A 2	1.050	1.150	1.250	e	0.950BSC		
b	0.300	0.400	0.500	e1	1.800	1.900	2.000
c	0.100	0.150	0.200	L	0.300	0.450	0.600
D	2. 820	2.920	3. 020	θ	0 °	4 °	8 °

The unit in the figure is mm. If no tolerance is specified, it is  $\pm 0.05$ .

### Pin Definition

Bonding point number	Function Symbol	Functional Description
5	RFIN	RF signal input terminal
1,3	RFOUT	RF signal output terminal
2, 4, 6	GND	The bottom of the chip needs to be well grounded to RF and DC

### Assembly diagram



## Precautions for use

- Sealing material : Low-pressure injection molding plastic that meets ROHS specifications
- Lead frame material: copper alloy
- Lead surface plating: 100% matte tin
- Maximum reflow peak temperature: 260 °C

### Use restriction parameter <sup>1</sup>

Maximum input power	+30dBm (CW)
Operating temperature	-40 ~ + 100 °C
Storage temperature	-65 ~ +150°C

【1】 Exceeding any of these maximum limits may cause permanent damage.